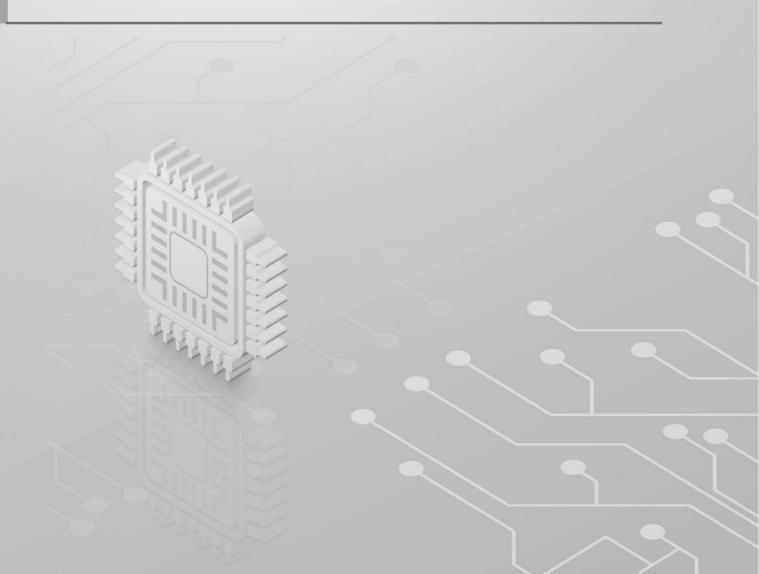


CM121 User Manual



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Revision History

Revision	Revision Record	Date
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Preface

This manual provides users with information about the hardware features, performance specifications, and usage guidelines of CM121 single-frequency multisystem positioning module.

Target Readers

This manual is intended for use by technical personnel. It is not aimed at the general readers.



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1. Product Overview

CM121 is a new-generation single-frequency, multi-constellation meter-level positioning module independently developed by ICOE. It simultaneously supports GPS L1, BDS B1I/B1C*, GLONASS L1, Galileo E1, and QZSS L1 systems.

The module incorporates the latest generation low-power RF baseband integrated GNSS SoC design, delivering meter-level positioning accuracy while maintaining optimal power efficiency. This module is applicable to various scenarios requiring high positioning accuracy coupled with low power consumption.

CM121 module features a compact 10.1x9.7x2.5mm SMT-compatible package with standard pads layout, supporting pick-and-place assembly and reflow soldering processes.

The module is commonly used in navigation and positioning applications including trackers, two-way radios, portable devices, two-wheeled vehicles and so on.



Fig. 1-1 CM121 Module Physical Diagram

		System			Interfaces			Data			
rrial			ASS	_			0	1			Update
Industr Grade	3PS	BDS	LON.	Galileo	SSZ	3AS	ART	ART	C	1	Rate
T 5	Ü	B	15	Ğ	Ò	SB	Ü	Ū	12	SPI	
•	•	•	•	•	•		•		*		1Hz~5Hz

Table 1-1 Key Features



1.1. Key Features

- Supports simultaneous multi-constellation positioning with BDS, GPS, GLONASS, Galileo, QZSS.
- High sensitivity with acquisiton sensitivity ≤-149dBm and tracking sensitivity ≤
 -165dBm.
- Integrated anti-jamming technology features real-time interference detection and suppression. Total anti-jamming capability is not less than -75dBm.
- Low power consumption: the power consumption is 13.5mA@3.3V in continuous tracking mode.
- Data update frequency up to 5Hz
- 10.1 x 9.7 x 2.5mm, 18-pin LCC package

1.2. Technical Specifications

Performance					
	GPS: L1C/A				
	BDS: B1I, B1C				
Operating Frequency	Galileo: E1B/C				
	GLONASS: G1				
	QZSS: L1C/A				
	Cold Start	-149dBm			
Considerate.*	Warm Start	-155dBm			
Sensitivity*	Re-acquisition	-159dBm			
	Tracking	-165dBm			
Horizontal Positioning Accuracy	2.0m (CEP50, Open Sky)				
Rate Accuracy*	0.1m/s				
	Cold start: 26s				
TTFF*(CEP50)	Hot start: 1s				
	Recapture: 2s				
Power Supply					
Input Voltage	2V~3.6V				
Power Consumption* Tracking	13.5mA@3.3V				



	Acquisition	16.2mA@3.3V
RF Input		
Input Gain		5dB~35dB
Input Impedance		50Ω
Input Power (Max)		10 dBm
Physical Characteristics		
Dimension		10.1mm×9.7mm×2.5mm
Environment		
Working Temperature		-40°C~+85°C
Storage Temperature		-40°C~+85°C
Humidity		35%~75%
Vibration		GB/T2423.10
Shock		GB/T2423.5
Communication Interfac	ce	
UART		1
I2C ¹		1

Table 1-2 CM121 Module Specifications

¹The function will be available in customized versions. *Test environment: -130dBm signal under the simulator at 25°C



2. Module Overview

2.1. System Block Diagram

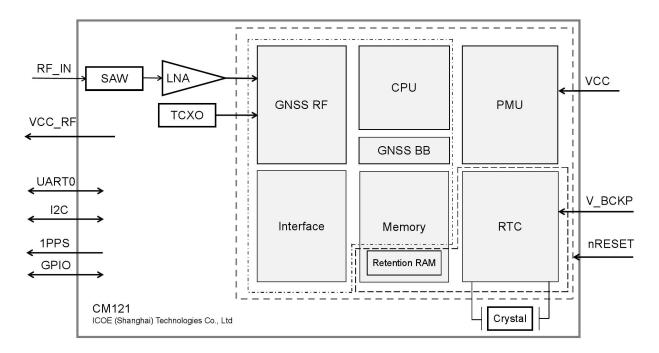


Figure 2-1 CM121 module block diagram

2.1.1. Communication interfaces

The CM121 supports one UART interface (UART) and one I2C1 interface.

UART

TXD and RXD pins operate at 115,200bps by default, with a maximum baud rate of 4 Mbps. Baud rate can be adaptive or manually configured.

UART interface supports data transmission and firmware upgrade function.

In order to support the firmware upgrade function, it is necessary to ensure that the UART is connected to a PC or external processor.

● **I2C**¹

The I2C interface can works in master mode to connect to the external sensor and support 100kbps, 400kbps and 1Mbps transmission rates.

2.1.2. 1PPS



1PPS outputs pulse sequence synchronized with GPS or UTC time grid, and the pulse width and polarity can be configured.

All input and output signals are synchronized with the internal clock frequency of the receiver, so that the inherent maximum quantization error of the signal reaches ± 20 ns.

2.1.3. Reset (nRESET)

Input signal, active low;

The low level duration of the reset signal remains not less than 5ms.

2.2. Package and Pin Definition

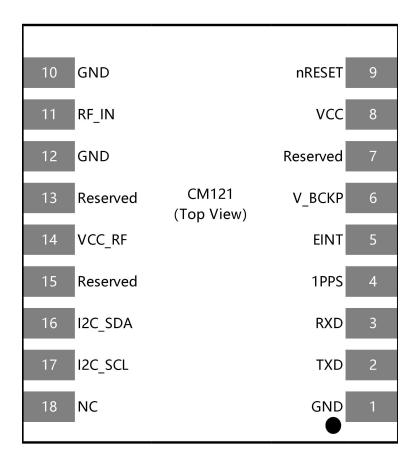


Figure 2-2 Pinout (Top View)

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Pin	Pin Name	Direction ²	Level	Description
No.	rin Name	Direction	Standard	Description
1	GND	-		Ground
2	TXD	О	LVTTL	Serial output
3	RXD	I	LVTTL	Serial input
4	1PPS	О	LVTTL	One pulse per second If unused, keep open
5	EINT	I	-	External Interrupt Input
6	V_BCKP			Backup power supply Connect VCC if the backup power is not used.
7	Reserved	-	-	Reserved
8	VCC	I	LVTTL	Main power supply Input voltage range: 2V~3.6V
9	nRESET	I	LVTTL	Reset the module, active low Connected to master GPIO or floating
10	GND	-		Ground
11	RF_IN	I/O		RF signal input, 50Ω impedance control
12	GND	-		Ground
13	Reserved	-	-	Reserved
14	VCC_RF	О		Power supply for external antenna, voltage same as 8-pin VCC
15	Reserved	-	-	Reserved
16	I2C_SDA	I/O	LVTTL	I2C Data Signal
17	I2C_SCL	I/O	LVTTL	I2C Clock Signal
18	NC	-	-	NC

Table 2-1 Pin Descriptions

Notes: IO levels are determined by VCC supply.

² Direction: I--input, input; O--output, output; I/O--bidirection;



2.3. Mechanical Dimensions

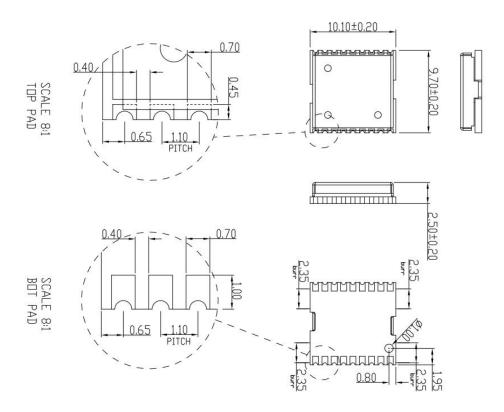


Figure 2-3 Mechanical Dimensions (Unit: mm)



3. Electrical Characteristics

3.1. Absolute Maximum Ratings

Parameter	Symbol	Minimum value	Maximum value	Unit
Power Supply Voltage	VCC	-0.3	3.6	V
Backup Voltage	V_BCKP	1.7	3.6 V	V
Input Pin Voltage	V _{in}	-0.3	3.6 V	V
Input Power of RF_IN	P _{RF_IN}		10	dBm
Output voltage of External LNA	VCC_RF	-0.3	3.6	V
Storage Temperature	Tstg	-40	85	°C

Table 3-1 Absolute Ratings

3.2. Operating conditions

Parameter	Symbol	Minimum value	Typical value	Maximum value	Unit	Condition
Supply Voltage	VCC	2		3.6	VCC	
VCC Maximum Ripple	Vrpp			50	mV	
Operating Current ³ (VCC=3.3 V)	Iopr		13.5	20	mA	
Operating	Topr	-40		85	°C	

³Operating current: Due to the capacitors inside the product, an inrush current will be generated during power-up. In practical applications, it is necessary to evaluate and confirm the impact of voltage dips caused by inrush current on the system.

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Parameter	Symbol	Minimum value	Typical value	Maximum value	Unit	Condition
temperature						
Tracking power consumption (VCC = 3.3 V)	P		45		mW	

Table 3-2 Recommended Operating Conditions

3.3. IO Threshold Characteristics

Parameter	Symbol	Minimum	Typical	Maximum	Unit	Condition
		value	Value	value		
Low-Level	Vin low	Vin low		0.2*VCC	V	
Input	VIII_IOW	VIII_IOW		0.2 VCC	v	
High-Level	Vin high	0.7*VCC		VCC+0.2	V	
Input	v III_IIIgII	0.7 VCC		V CC 10.2	•	
Low-Level		0		0.45 V	Iout = 4	Iout = 4
Output	Vout_low	U		0.43 V	mA	mA
High-level		VCC-0.45		VCC	Iout = 4	Iout = 4
output	Vout_high	VCC-0.43		VCC	mA	mA

Table 3-3 IO Threshold Characteristics

3.4. Antenna Characteristics

		Minimum	Typical	Maximum		
Parameter	Symbol	value	value	value	Unit	Condition
Input Gain	Gain	5		35 dB	dB	

Table 3-4 External Antenna Characteristics



3.5. External Antenna Feed Design

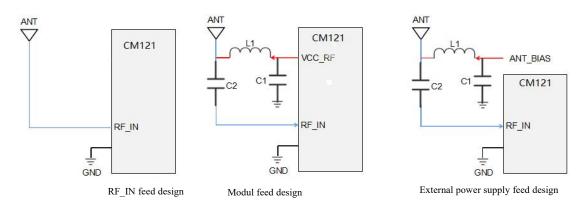


Fig. 3-5 External antenna feed reference circuit

- L1, feed inductor, 68nH RF inductor recommended
- C1, decoupling capacitor, parallel combination of 100nF and 100pF capacitors recommended
- C2, RF DC-Blocking (or DC-Isolating) Coupling Capacitor
- L1, C1, C2 and CM121 module need to be placed close to the antenna feed point;
- External antenna feed mode:

If the antenna detection function is required, it is necessary to match the peripheral matching circuit and use the output V_ANT of the antenna detection circuit to feed the external antenna (module feed design);

If the antenna detection function is not required,, it is recommended to use external power supply to feed the external antenna directly (external power supply feed design).

- Red line: power supply line of antenna feed
- Blue line: RF trace, 50Ω impedance control is required
- RF IN feed design is not recommended for passive antenna configuration



4. Production requirements

The recommended soldering temperature profile is shown below:

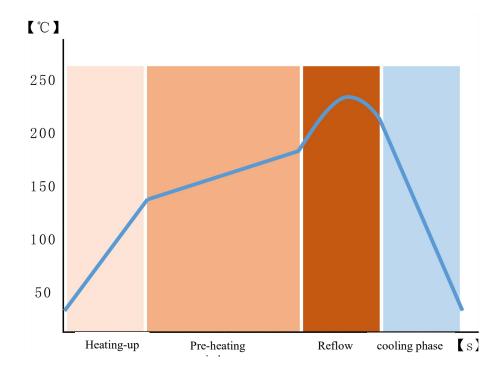


Figure 4-1 Lead-Free Reflow Solder Temperaure Curve

Lead-Free	Ramp-up	Preheat	Reflow Phase	Cooling Phase
Process	Phase	Phase	Kellow Fliase	Cooling Fliase
Temperature Zone (°C ⁴)	50~150	150~180	>217(melting point) and < 245	< 217
Ramp Rate (°C/s ⁵)	< 3			≤4
Duration (s)	~50	60~120	40~60(> 217°C)	~40
Remarks	Ramp-up Rate: <3°C/s		The peak reflow temperature shall not exceed 245°C	Ramp-down Rate: max. 4°C/s

Table 4-1 Lead Free Process Parameter Table

⁴ °C: degrees Celsius

⁵ °C/s: degrees Celsius per second.





- To prevent the module from falling off during soldering, please do not design the module to be soldered on the back of the board. Dual reflow cycles are strongly discouraged.
- 2. The setting of soldering temperature depends on many factors in the product factory, such as PCB substrate characteristics, type of solder paste, thickness of the paste, etc. Please also refer to the relevant IPC standards as well as specifications of the solder paste.
- 3. Due to the relatively low temperature of Pb-containing solder, please prioritize other components on the board if using this soldering method.
- 4. Stencil aperture design should meet the customer-specific design requirements and inspection criteria.
- 5. Stencil thickness should be no less than 0.12mm, with 0.15mm recommended as standard."



5. Packaging

5.1. Labeling



Fig. 5-1 Product Label

5.2. Packaging

CM121 module is vacuum-sealed in an anti-static aluminum foil bag with desiccant for moisture protection and is supplied in carrier tape & reel packaging for compatibility with mainstream SMT (Surface Mount Technology) equipment.

When soldering the module using reflow processes, strictly adhere to IPC standards for humidity control. Since the carrier tape and other packaging materials can only withstand temperatures up to 55°C, the module must be removed from its packaging before baking.

Parameter	Description				
Reel Quantity	1000pcs/roll				
	Reel: 13 inches				
Reel Size	Outer diameter: 330mm, Inner diameter: 100mm, Width: 24mm,				
	Wall thickness:2mm.				
Carrier Tape	Module pitch (center distance): 16mm				

Table 5-2 Tape & Reel Packaging Specifications

CM121 LCC package is rated at MSL level 3. Baking requirements should comply with IPC/JEDEC standards (available for download at www.jedec.org).

The shelf life of CM121 module is one year.





- After opening the vacuum-sealed bag, SMT placement must be completed within 48 hours when ambient conditions are maintained at: Temperature: <30°C and Relative Humidity: <60% RH.
- 2. In original intact aluminum foil vacuum packaging (undamaged/airtight), the shelf life is 12 months when stored under: Temperature: 18°C to 28°C (controlled environment) and Relative Humidity: <60% RH.

6. Ordering Information

Model Number	Package Size	Operating Temperature	Grade	Function	Packaging
CM121-11	10.1x9.7x2.5mm	-40~+85°C	Industrial Grade	Single Frequency PVT DCDC Configuration	Tape and Reel Packaging. 1000 pcs/roll

Table 6-1 Ordering Information Sheet





Floor 8, Building 1, Lane 500, Shengxia Road, China (Shanghai) Pilot Free Trade Zone 200120
Web: http://www.icoe-tech.com
Tel: 021-58213950 Fax: 021-58213950